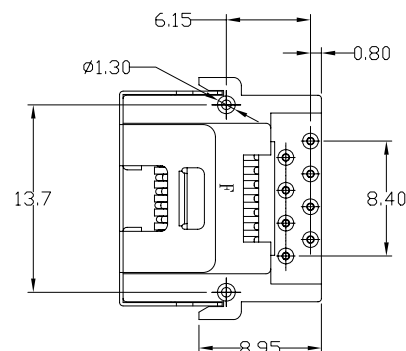
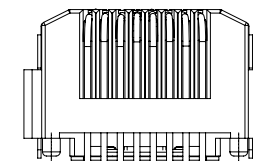
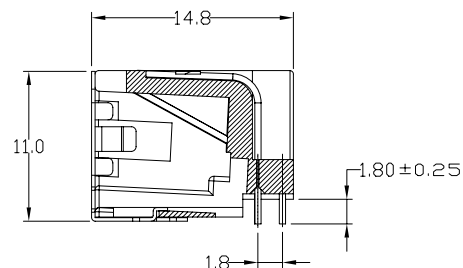
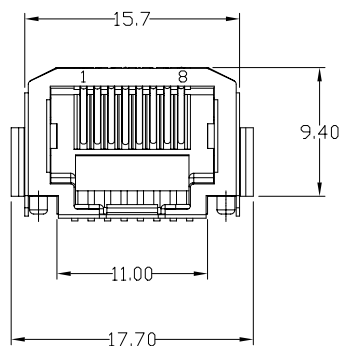


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD
△		ADD P/N.	HERO 12/13/05	



NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE : 1000 MEGOHMS MIN @ 500 VDC
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60HZ, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : PA66+30%G.F FR52UL94V- 0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE Ø0.46mm
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POS-SOLDER : 10 LBS MIN.

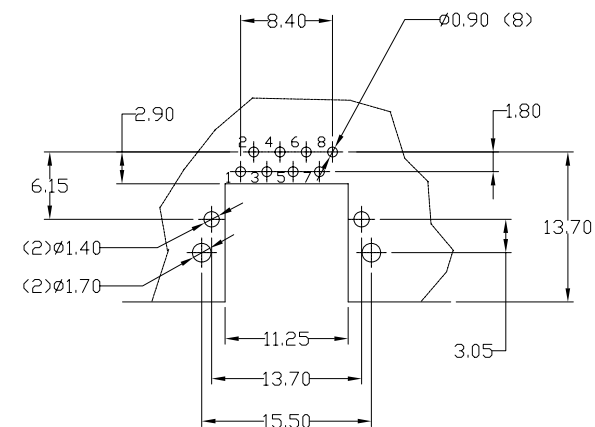
ENVIRONMENTAL:

1. STORAGE : -40°C TO +80°C
2. OPERATION: 0°C TO +70°C
3. WAVE SOLDERING TEMPERATURE: 255~265°C (5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.
FREE LEAD PART NUMBER: E6688-2C0XXX-L

GOLD PLATING
1- 3u" 2-6u"
3-15u" 4-30u"
5-50u"

22-FR52 BK
82 PA66+30%G.F BK △



PC BOARD Thickness=0.60 ~ 0.80mm
PC BOARD LAYOUT COMPONENT SIDE SHOWN

DETACHED LISTS	MM (INCH)	DFTD YAN	DATE 04/25/05	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED	CHKD	DATE		
	MM	MFD	DATE	TITLE	
	.0 ± 0.2	APPVLOSCAR	DATE 12/14/05	RJ45-66DIP(8P)	
	.00 ± 0.15			DRAWING NO. GE663A03-LA	
ANGLES ± 0.5		MATERIAL :		/PART NO. SEE NOTE	
THIRD ANGLE PROJECTION		QT'Y :		SIZE A3	
		FINISH:		REV 1	
		SCALE : 2:1		DO NOT SCALE DRAWING	
				SHEET 1 OF 1	